



SOT322-2

plastic quad flat package; 160 leads (lead length 1.6 mm);
body 28 x 28 x 3.4 mm; high stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QFP160
Package type industry code	QFP160
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	135E12
JEDEC package outline code	MS-022
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	3.2	-	3.4	3.6	mm
A ₂	package height	[tbd]	-	3.4	[tbd]	mm
n ₂	actual quantity of termination	-	-	160	-	

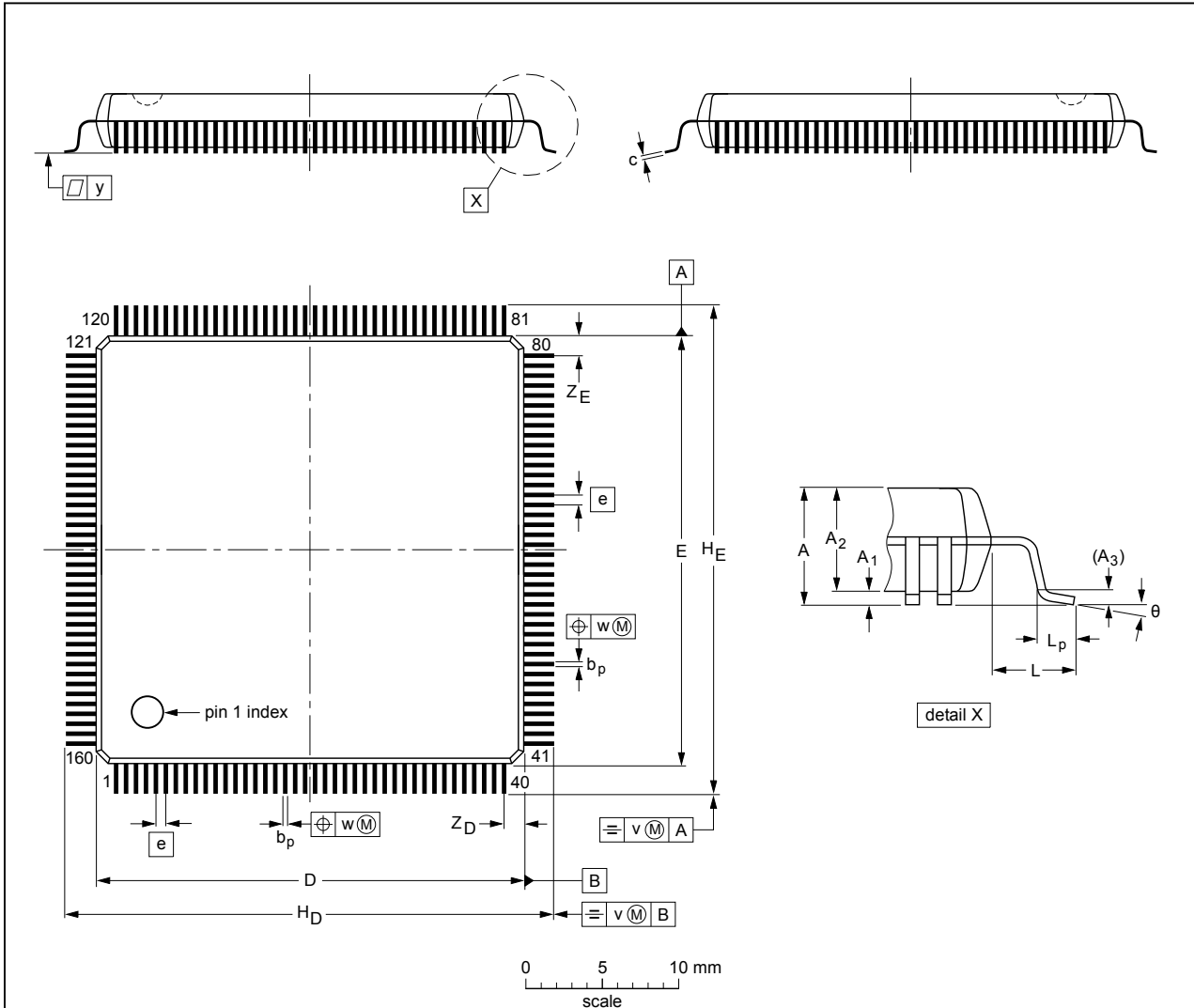


plastic quad flat package; 160 leads (lead length 1.6 mm); body 28 x 28 x 3.4 mm; high stand-off height

2. Package outline

QFP160: plastic quad flat package;
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	4.07	0.50 0.25	3.6 3.2	0.25	0.38 0.22	0.23 0.13	28.1 27.9	28.1 27.9	0.65	31.45 30.95	31.45 30.95	1.6	1.03 0.73	0.3	0.13	0.1	1.5 1.1	1.5 1.1	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT322-2	135E12	MS-022				00-01-19 03-02-25

Fig. 1. Package outline QFP160 (SOT322-2)

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3. Soldering

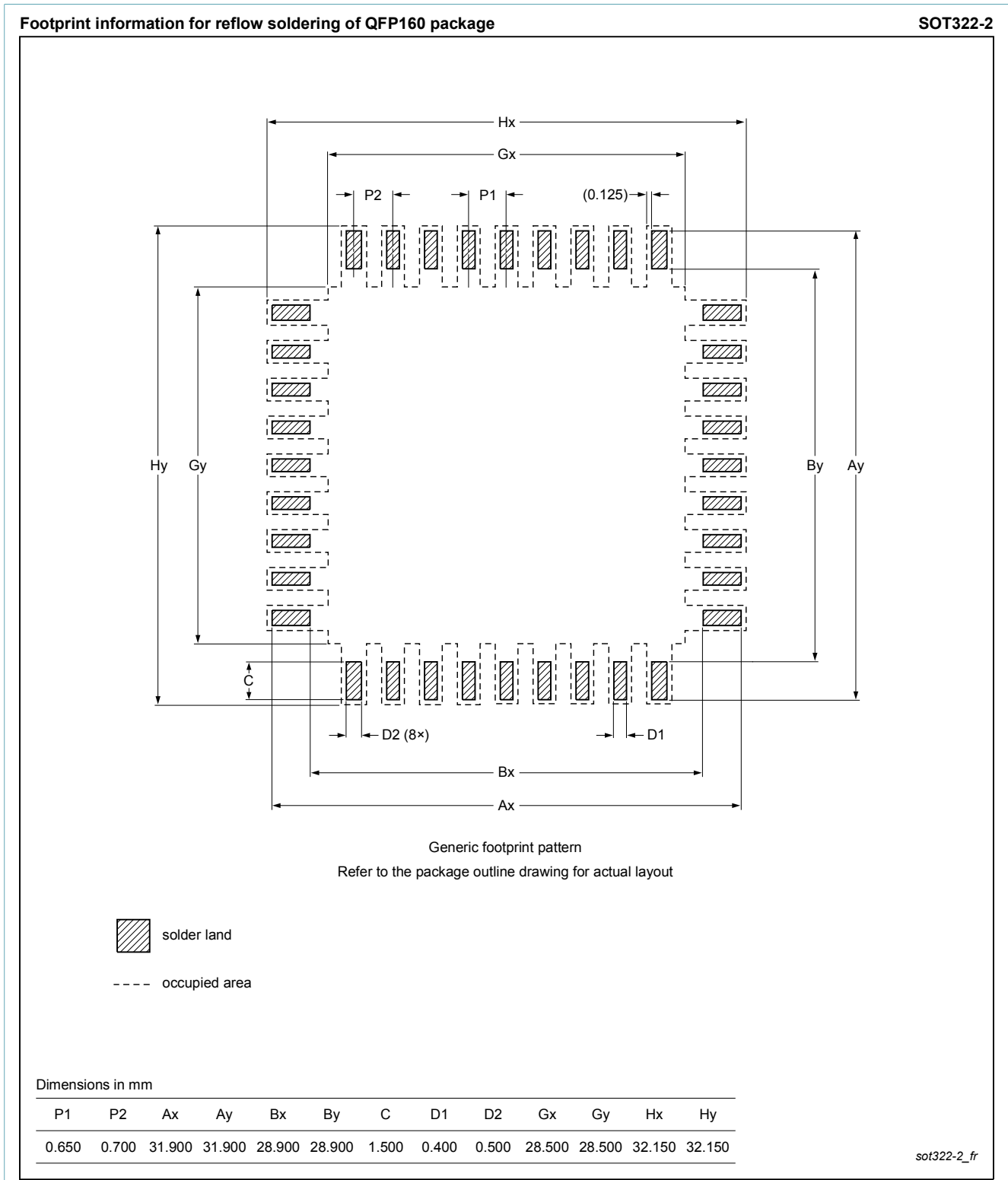
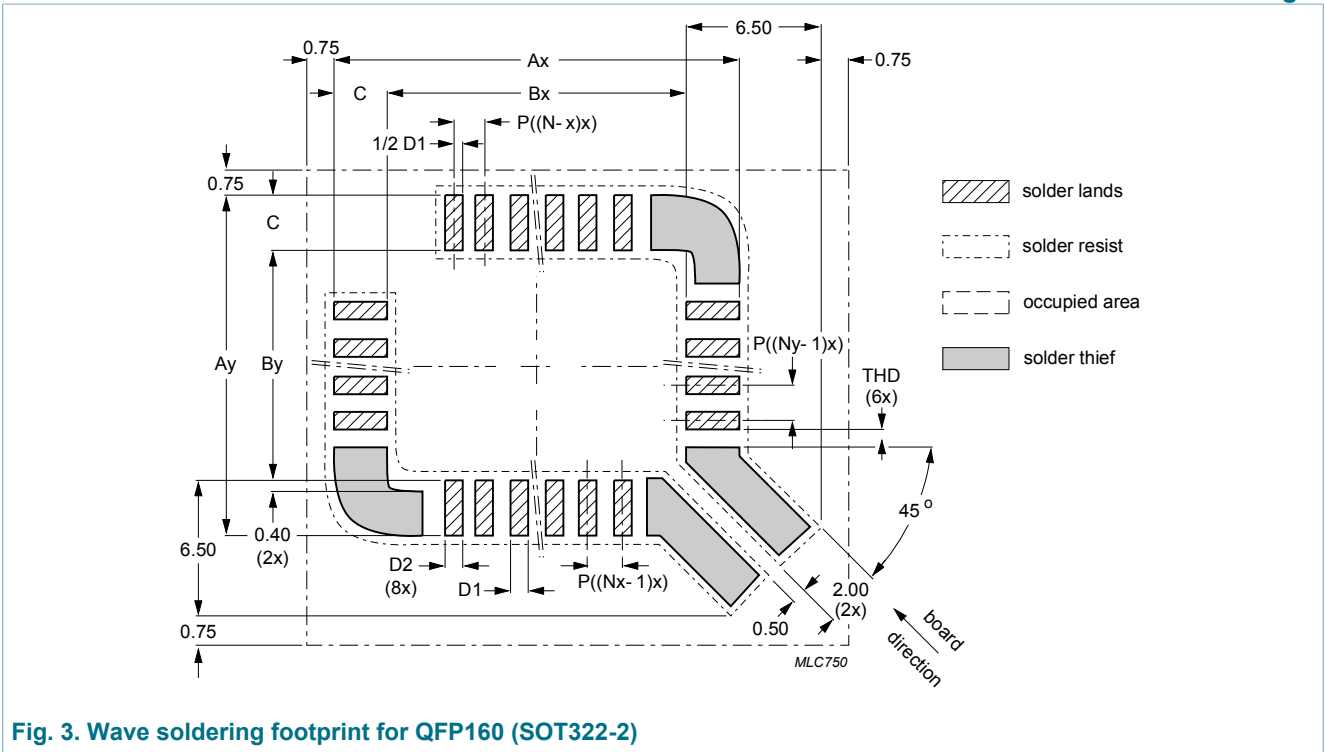


Fig. 2. Reflow soldering footprint for QFP160 (SOT322-2)

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4. Legal information

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